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IWLPC panel explores business and marketing issues of wafer-level packaging

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A panel of expert industry analysts will discuss key business and marketing issues in wafer-level and integrated circuit packaging at the third annual International Wafer-Level Packaging Conference (IWLPC).

The IWLPC, co-presented by Chip Scale Review and the SMTA, will take place from November 1-3, 2006, at the Wyndham Hotel, San Jose. November 1 is dedicated to special workshops. November 2-3 will include technical presentations and exhibits by industry vendors.

The panel is scheduled from 8-10 a.m. on Thursday, November 2. Panelists will include Morry Marshall of Semico Research Corp., Jan Vardaman of TechSearch International, Jim Walker of Gartner-Dataquest and Sandra Winkler of Electronic Trend Publications.

Walker will lead-off with a presentation on "Market Dynamics and Recent Advances in Technology and Applications for 3D, WLP and Stacked Wafers."

His discussion will be followed by Vardaman, who will address "The Expansion of Wafer-Level Packaging: Challenges and Opportunities." Next, Winkler will report on "The IC Packaging World and its Latest Developments."

Finally, Semico's Marshall will examine "Drivers for Stacked Chip-Scaled Package Technology."

Following the individual presentations, panelists will answer questions from the audience. This is the third appearance of the panel, which has attracted a standing-room-only audience each year.

More information and online registration is available at www.smta.org/iwlpc.